

| L<br>Number | Hits | Search Text   | DB                             | Time stamp          |
|-------------|------|---|--------------------------------|---------------------|
| 1           | 3    | "6646332"   | USPAT;<br>EPO; JPO;<br>DERWENT | 2004/07/24<br>21:52 |
| 2           | 2476 | semiconductor with package and (vias or holes) and solder and adhesive                    | USPAT;<br>EPO; JPO;<br>DERWENT | 2004/07/24<br>21:54 |
| 3           | 7    | "multi-layer" adj2 semiconductor with package and (vias or holes) and solder and adhesive | USPAT;<br>EPO; JPO;<br>DERWENT | 2004/07/24<br>21:54 |